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Modeling and optimization of the sandwich beam specimen in three-point bending for adhesive bond characterization

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ABSTRACT

Standard tests for adhesive bond characterization suffer for several deficiencies. The simplest specimens to make and test are lap joint geometries (e.g. single, double, symmetric, etc.) that generate complex stress distributions with irregularities and even singularities of the stress state. Those with the stress state closer to pure shear (e.g. napkin ring or Arcan) are difficult to make and require special test fixtures. This paper examines the stress state in the adhesive of a simple beam specimen obtained by bonding two flat plates one upon the other and loading the final sandwich in three-point bending. An elementary theory is used to optimize the specimen for in-situ measurements of either shear strength or shear modulus of the adhesive. The accuracy of the model is validated with finite element analyses, showing good agreement between the analytical and finite element model and also providing suggestions for the best geometry to be adopted for practical implementation of the test.

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1. Introduction

Proper design of bonded joints requires reliable information on the mechanical properties of the adhesive in specific application conditions. When adhesives are tested in bulk (neat resin), the measured constitutive properties may not be representative of those in bonded state on three grounds: a) the chemical effect of the adhesive–adherend interphase is lost [1]; b) the adhesive stress triaxiality generated in-situ by the adherends cannot take place [2]; c) the curing conditions may differ because of uncontrolled runaway exothermic reactions in bulk forms [2]. All bond properties are affected [3–5] but the influence on Young's modulus is especially significant [6]. Furthermore, not all adhesive products can be cast as bulk specimens.

Well established tests coupons that include information about the condition of the interface are single, double or other lap specimen configurations [7,8]. However simple to make and test, these geometries have complex stress distributions within the bond and give rise to both normal (peel) and shear stresses that vary from point to point [9,10]. Stress singularities at re-entrant corners and at points of material discontinuity are also an issue [11] that undermine the meaning of these tests for providing genuine strength properties of the adhesive [12–14].

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Efforts over the years have been devoted to the development of specimen geometries in which only a single pure shear stress state exists. A notable example in this category is the napkin ring torsion test, either in the standard flat-on-flat configuration [15] or in the cone-on-flat modification [16], which ensures a near-uniform shear stress on the adhesive. A variant of the napkin ring test is the solid butt joint in torsion [2]. This is easier to make than the napkin ring and the Nadai correction gives true stress and strain in the adhesive over the radius. A butt-bonded beam under antisymmetric bending producing a state of simple shear over the bondline was proposed by Wycherley et al. [17] as an adaptation of the famous shear test for metals due to Iosipescu [18]. A uniquely shaped specimen to measure shear stress using an axial tension test machine was introduced by Arcan and coworkers [19]. The only measurements needed in Iosipescu and Arcan tests for shear modulus and shear strength determination are the applied load, the dimensions of the adhesive layer and the relative displacement between the adherends along the bondline. However, elaborate fixtures are needed for proper loading and very precise notches (Iosipescu) and groves (Arcan) must be machined in the specimens to ensure uniformity of stresses and removal of singularities [20]. Also, the application of the load and the measurement of the relative displacement across the adhesive layer are not simple tasks, which require special equipment to be performed correctly. For these reasons, use of these specimens is generally confined to research environments.

Aimed at providing a simple method for routine measurement of adhesive properties, in the late 80s Moussiaux, Cardon and

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Nomenclature	$\alpha_{L\sigma}^{*}$ Threshold value of α_{L} for bond stress optimization
	$\gamma_a(x)$ Shear deformation of the conductor layer
b Width of beam	6 Center deflection of the barraneous barra
C_a Correction factor for the deflection of th	$he = o_0$ Center deflection of the homogeneous beam
sandwich beam	$o_{0 cr}$ Center deflection of the homogeneous beam under
L Half-length of the sandwich beam	Force P_{cr}
$(L/h)_{max}$ Minimum between $(L/h)_{\delta}$ and $(L/h)_{\sigma}$	$(\delta_{0 cr}/L)_{lim}$ Limit relative deflection acceptable for the
$(L/h)_{\delta}$ Limit aspect ratio to avoid excessive deformation of	of sandwich beam
the sandwich	η, ξ Dummy coordinates used for integration with respect
$(L/h)_{\sigma}$ Limit aspect ratio to avoid overstress of the adherend	ls to x
<i>E</i> , <i>G</i> Young's modulus and shear modulus of the adherend	$\mu_{\rm Is}$ ν Poisson's ratio of the adherends
E_a , G_a Young's modulus and shear modulus of the adhesive	ν_a Poisson's ratio of the adhesive
<i>h</i> Thickness of the adherends	σ_{adm} Admissible working stress of the adherends
<i>I</i> Bending moment of inertia of the section of each	σ_b Normal stress in adherend's cross-section due to
adherend ($=bh^3/12$)	bending
<i>P</i> Transverse force acting on beam ends	σ_{max} Maximum bending stress in the adherends
<i>P_{cr}</i> Transverse force producing failure of the adhesive	σ_{maxcr} Maximum bending stress in the adherends under
<i>t_a</i> Thickness of the adhesive layer	force P _{cr}
$(t_a/h)_{max}$ Max allowed relative thickness of bondline for stres	$\sigma_{\rm N}$ Normal stress in adherend's cross-section due to
optimization	axial force
u_a, u_b, u_s Axial displacements of adherends and adhesive th	The $\tau(x)$ Shear stress in the adhesive layer
interface	$\tau_{a cr}$ Critical stress of the adhesive
w(x) Transverse deflection of beam at position x	τ_0 Maximum shear stress in the homogeneous beam
<i>x</i> Distance from beam center along the beam axis	τ_{max} Maximum shear stress in the adhesive layer
α_{I} Relative stiffness of the adhesive layer	$\overline{ au}_{max}$ Limit value of the maximum shear stress in the
α_{ls}^{*} Optimal value of α_{l} for measurement of the adhesiv	e adhesive layer
shear modulus	

Brinson introduced a bonded double cantilever beam specimen [21], which develops a pure shear stress in the adhesive layer. With this easy to make specimen, adhesive properties (shear strength and shear modulus) can be obtained from a standard three-point bend test using the direct readings of force and displacement supplied by the testing machine. With fixed-fixed boundary conditions, the sandwich specimen can also be used in dynamic mechanical thermal analysis (DMTA) systems to obtain viscoelastic shear properties under a range of temperatures and adhesive-adherend interface conditions [22-24].

The basic theory providing the stress distribution in the adhesive and the overall sandwich beam deflection was provided in [21] and further elaborated in [22,23] for different constraint conditions. The theory in this form was assessed in [25] for the beam compliance by means of finite element analyses, showing that it tends to overestimate the beam stiffness especially for lowmodulus adhesives and thin adherends. Hunston and coworkers [24] applied the original theory for analyzing the viscoelastic



Fig. 1. Schematic of the sandwich beam in the undeformed (a) and deformed (b) configurations.

properties of rubbery and glassy adhesives and found encouraging results. A sensitivity analysis of the beam stiffness on the shear modulus of the adhesive was also carried out. An interesting refinement of the theory was proposed by Brinson and coworkers in [26] and used to interpret the results from DMTA testing.

Most papers available on the bonded sandwich beam focus on the determination of the adhesive shear modulus, while the adhesive shear strength is much disregarded. Further, a comprehensive analysis of the merits and the limitations of the test to get information on a wide range of adhesive properties is missing. Using the equations available in [26], this paper aims at optimizing the geometry of the sandwich beam in view of the property to be



Fig. 2. Bonded sandwich beam and free body diagrams of individual elements with corresponding stress states.

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